

11/26/01

Class	Subclass	ISSUE CLASSIFICATION
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PATENT NUMBER

U.S. UTILITY Patent Application

12W O.I.P.E. PDY 84
SCANNED 450 Q.A. 1M

PATENT DATE

APPLICATION NO.
09/994395

CONT/PRIOR

CLASS
257

SUBCLASS
750

ART UNIT	2811
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EXAMINER

Th. Meyer

APPLICANTS

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Paul Besser
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TITLE

Method of using ternary copper alloy to obtain a low resistance and large grain size interconnect

PTO-2040
12/99

ISSUING CLASSIFICATION

ORIGINAL				CROSS REFERENCE(S)							
CLASS		SUBCLASS		CLASS	SUBCLASS (ONE SUBCLASS PER BLOCK)						
INTERNATIONAL CLASSIFICATION											

<input type="checkbox"/> TERMINAL DISCLAIMER	DRAWINGS Sheets Drwg. Figs. Drwg. Print Fig. <u>4</u>		CLAIMS ALLOWED Total Claims Print Claim for O.G.	
	<input type="checkbox"/> The term of this patent subsequent to _____ (date) has been disclaimed. _____ (Assistant Examiner) _____ (Date)		NOTICE OF ALLOWANCE MAILED	
<input type="checkbox"/> The term of this patent shall not extend beyond the expiration date of U.S. Patent No. _____	_____ (Primary Examiner) _____ (Date)		ISSUE FEE	
			Amount Due	Date Paid
<input type="checkbox"/> The terminal _____ months of this patent have been disclaimed.	_____ (Legal Instruments Examiner) _____ (Date)		ISSUE BATCH NUMBER	

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